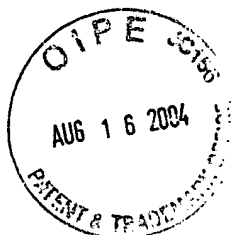


IMEC182.001C1C1



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Satta et al.
Appl. No. : 10/731,656
Filed : December 8, 2003
For : METHOD FOR BOTTOMLESS
DEPOSITION OF BARRIER
LAYERS IN INTEGRATED
CIRCUIT METALLIZATION
SCHEMES

Examiner : David Nhu
Group Art Unit : 2818

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

August 11, 2004

(Date)

A handwritten signature in black ink, appearing to read "A. N. Merickel", written over a horizontal line.

Andrew N. Merickel, Reg. No. 53,317

RESPONSE TO OFFICE ACTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The present paper is submitted in response to the Office Action mailed on May 11, 2004. Applicants respectfully request consideration of the following remarks.

Amendments to the Figures begin on page 2 of this paper

Remarks/Arguments begin on page 3 of this paper.

Appl. No. : **10/731,656**
Filed : **December 8, 2003**

AMENDMENTS TO THE FIGURES

Figure 1 has been amended to add the label "Prior Art" as requested by the Examiner.